



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN# 20250307000.1**

**Qualification of RFAB using qualified Process Technology, Die Revision, Datasheet  
and additional Assembly site options for select devices  
Change Notification / Sample Request**

**Date:** March 10, 2025  
**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team  
SC Business Services

**20250307000.1**  
**Change Notification / Sample Request**  
**Attachments**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
SN74AVC1T45DCKR	SN74AVC1T45DCKR
SN74AVC1T45DBVR	SN74AVC1T45DBVR
SN74AVCH1T45DCKR	SN74AVCH1T45DCKR

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20250307000.1			<b>PCN Date:</b>	March 10, 2025																		
<b>Title:</b>	Qualification of RFAB using qualified Process Technology, Die Revision, Datasheet and additional Assembly site options for select devices																						
<b>Customer Contact:</b>	Change Management team		<b>Dept:</b>	Quality Services																			
<b>Proposed 1<sup>st</sup> Ship Date:</b>	June 08, 2025		<b>Sample requests accepted until:</b>	May 09, 2025																			
<b>*Sample requests received after May 09, 2025 will not be supported.</b>																							
<b>Change Type:</b>																							
<input checked="" type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material																		
<input checked="" type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process																		
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site																		
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Material																		
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process																		
<b>PCN Details</b>																							
<b>Description of Change:</b>																							
Texas Instruments is pleased to announce the addition of RFAB using the qualified LBC7 process technology, die revision, data sheet and additional assembly site option for the device listed below.																							
<table border="1"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">Additional Fab Site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Additional Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>FR-BIP-1</td> <td>ASLC10</td> <td>200 mm</td> <td>RFAB</td> <td>LBC7</td> <td>300 mm</td> </tr> </tbody> </table>			Current Fab Site			Additional Fab Site			Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter	FR-BIP-1	ASLC10	200 mm	RFAB	LBC7	300 mm			
Current Fab Site			Additional Fab Site																				
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter																		
FR-BIP-1	ASLC10	200 mm	RFAB	LBC7	300 mm																		
The die was also changed as a result of the process change.																							
Construction differences are as follows;																							
<b>Group 1 Device</b>																							
	<b>HNA</b>		<b>CDAT</b>																				
Wire diam/type	1.0mil Au		0.8mil Cu																				
Mount compound	SID#400180		4207123																				
Mold compound	SID#450207		4222198																				
Lead finish	NiPdAu		Matte Sn																				
<b>Group 2 Device</b>																							
	<b>HNA</b>		<b>CDAT</b>	<b>HFTF</b>																			
Wire diam/type	1.0mil Au		0.8mil Cu	0.8mil Cu																			
Mount compound	SID#400180		4207123	SID#A-03																			
Mold compound	SID#450179		4222198	SID#R-27																			
Lead finish	NiPdAu		Matte Sn	Matte Sn																			
<p>Upon expiry of this PCN, TI will combine lead finish solutions in a single standard part number. For example, a customer order for 7500 units of a specific TI part number with 2500 units SPQ (Standard Pack Quantity per reel) may be fulfilled in the following ways:</p> <ul style="list-style-type: none"> <li>• 3 reels of NiPdAu finish.</li> <li>• 3 reels of Matte Sn finish</li> <li>• 2 reels of Matte Sn and 1 reel of NiPdAu finish</li> <li>• 2 reels of NiPdAu and 1 reel of Matte Sn finish</li> </ul> <p>The datasheets will be changing as a result of the above-mentioned changes. The datasheet</p>																							

change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.



**SN74AVCH1T45**

SCES598F – JULY 2004 – REVISED APRIL 2024

Changes from Revision E (March 2016) to Revision F (March 2024)	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Updated DBV and DCK thermal information.....	5



**SN74AVC1T45**

SCES530K – DECEMBER 2003 – REVISED FEBRUARY 2025

Changes from Revision J (August 2024) to Revision K (February 2025)	Page
• Updated DCK and DBV <i>Thermal Information</i> .....	8

Changes from Revision I (March 2024) to Revision J (August 2024)	Page
• Updated Thermal Metrics.....	8

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
SN74AVCH1T45	SCES598E	<b>SCES598F</b>	<a href="http://www.ti.com/product/SN74AVCH1T45">http://www.ti.com/product/SN74AVCH1T45</a>
SN74AVC1T45	SCES530I	<b>SCES530K</b>	<a href="http://www.ti.com/product/SN74AVC1T45">http://www.ti.com/product/SN74AVC1T45</a>

Qual details are provided in the Qual Data Section.

#### Reason for Change:

Supply Continuity

#### Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

#### Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change

#### Changes to product identification resulting from this PCN:

##### Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FR-BIP-1	TID	DEU	Freising
<b>RFAB</b>	<b>RFB</b>	<b>USA</b>	<b>Richardson</b>

**Die Rev:****Current****New**

Die Rev [2P]	<b>Die Rev [2P]</b>
-	<b>A</b>

**Assembly Site Information:**

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
HNA	HNT	THA	Ayutthaya
<b>CDAT</b>	<b>CDA</b>	<b>CHN</b>	<b>Chengdu</b>
<b>HFTF</b>	<b>RFB</b>	<b>USA</b>	<b>Richardson</b>

Sample product shipping label (not actual product label)

**Group 1 Product Affected:**

SN74AVC1T45DBVR*	SN74AVCH1T45DBVR*	SN74AVCH1T45DCKR*
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**Group 2 Product Affected:**

SN74AVC1T45DCKR\*

\* G4 part numbers are available and will remain on NiPdAu flows. Please visit TI's labeling and symbolization page for more information on material designators.

**Group 1 Qualification Report (DBV)**

Approve Date 18-JULY -2024

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <u>SN74AVC1T45DBVR</u>	Qual Device: <u>SN74AVCH1T45DBVR</u>	QBS Reference: <u>SN3257QDYRQ1</u>	QBS Reference: <u>TLV9061IDBVR</u>	QBS Reference: <u>CAVC1T45QDCKRQ1</u>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	1/77/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	-	1/45/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	3/231/0	1/77/0
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	-	3/2400/0	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	-	3/228/0	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	3/228/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	3/66/0	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	-	3/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	-	1/10/0
ESD	E2	ESD CDM	-	1500 Volts	-	-	1/3/0	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	1/6/0	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	-	3/90/0
FTY	E6	Final Test Yield	-	-	-	-	-	3/3/0	-

QBS: Qual By Similarity

Qual Device SN74AVC1T45DBVR is qualified at MSL1 260C

Qual Device SN74AVCH1T45DBVR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

## Group 1 Qualification Report (DCK)

Approve Date 22-APRIL -2024

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <u>SN74AVC1T45DCKR</u>	QBS Reference: <u>SN3257QDYRQ1</u>	QBS Reference: <u>TLV9061IDBVR</u>	QBS Reference: <u>TXS0101DCKR</u>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	-	1/50/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	3/231/0	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	3/2400/0	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	3/228/0	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	3/228/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-

SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	3/66/0	1/22/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	3/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	1/3/0	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	-
FTY	E6	Final Test Yield	-	-	-	-	3/3/0	-

QBS: Qual By Similarity

Qual Device SN74AVC1T45DCKR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

## Group 2 Qualification Report (DCK-HFTF)

Approve Date 22-APRIL -2024

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <u>SN74AVC1T45DCKR</u>	QBS Reference: <u>SN3257QDYRQ1</u>	QBS Reference: <u>TLV9061IDBVR</u>	QBS Reference: <u>TXS0101DCKR</u>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	-	1/50/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	3/231/0	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	3/2400/0	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	3/228/0	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	3/228/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB- Free Solder;	-	-	-	3/66/0	1/22/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	3/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	1/3/0	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	-
FTY	E6	Final Test Yield	-	-	-	-	3/3/0	-

QBS: Qual By Similarity

Qual Device SN74AVC1T45DCKR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com>

## Group 2 Qualification Report (DCK-CDAT)

Approve Date 22-APRIL -2024

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">SN74AVC1T45DCKR</a>	QBS Reference: <a href="#">SN3257QDYYRQ1</a>	QBS Reference: <a href="#">TLV9061IDBVR</a>	QBS Reference: <a href="#">TXS0101DCKR</a>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	-	1/50/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	3/231/0	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	3/2400/0	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	3/228/0	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	3/228/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	3/66/0	1/22/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	3/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	1/3/0	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	-
FTY	E6	Final Test Yield	-	-	-	-	3/3/0	-

QBS: Qual By Similarity

Qual Device SN74AVC1T45DCKR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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